



AMM&NS Technical Programme Agenda

Monday, January 19, 2004

- 1330hr – 1345hr Fatal Void Size Comparisons in Via-Below and Via-Above Cu Dual-Damascene Interconnects
Z.S. Choi, MIT
- 1345hr – 1400hr Mortality Dependence of Cu Dual Damascene Interconnects on Adjacent Segments
C. W. Chang, NUS
- 1400hr – 1415hr Review of Direct Metal Bonding for Microelectric Interconnections
G. G. Zhang, NTU
- 1415hr – 1430hr Effect of Pt on agglomeration and Ge out-diffusion in Ni(Pt) germanosilicide
L. J. Jin, NUS
- 1430hr – 1445hr TiNi-based thin films for MEMS applications
Yongqing Fu, NTU
- 1445hr – 1500hr Synthesis, electrochemistry and First Principles Calculation studies of layered Li-Ni-Ti-O compounds
K. Kang, MIT
- 1500hr – 1515hr Combining Ab-Initio Computation with Experiments for Designing New Electrode Materials for Advanced Lithium Batteries: $\text{LiNi}_{1/3}\text{Fe}_{1/6}\text{Co}_{1/6}\text{Mn}_{1/3}\text{O}_2$
Shirley Y. Meng, NUS
- 1515hr – 1530hr Investigation on Thin Film Lithium Microbatteries
Z. Shi, NUS
- 1530hr – 1545hr **Break**
- 1545hr – 1600hr Mechanical Properties of Bulk Metallic Glasses and composites
M.L. Lee, NUS
- 1600hr – 1615hr Effect of Microstructure Changes on Mechanical Properties of $\text{La}_{66}\text{Al}_{14}(\text{Cu},\text{Ni})_{20}$ Amorphous and Crystalline Alloys
Yong Zhang, NUS
- 1615hr – 1630hr Growth and Properties of (001)-oriented $\text{Pb}(\text{Zr}_{0.52}\text{Ti}_{0.48})\text{O}_3/\text{LaNiO}_3$ Films on Si(001) Substrates with TiN Buffer layers
T.J. Zhu, NUS

End of Day 1